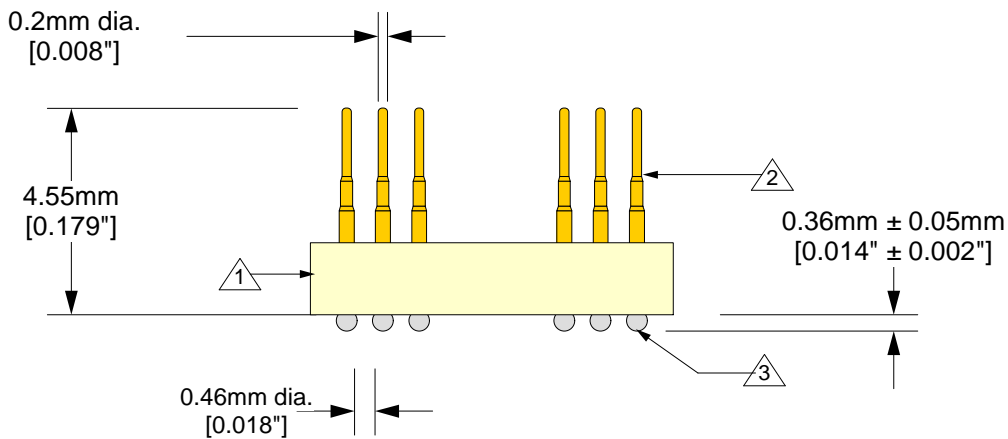


Top View




Side View

- 1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]  
FR4/G10 or equivalent high temp material;  
Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish-  
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- 3 Solder Balls: Sn63Pb37

**Description:** Giga-snaP BGA SMT Foot

60 position terminal pins (0.8mm centers, 8x10 array) to SMT solder balls (BGA type). Pin assignment 1:1.

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>© 2008 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p><b>SF-BGA60C-B-61 Drawing</b></p>	<p>Status: Released</p>	<p>Scale: 6:1</p>	<p>Rev: C</p>
	<p>Drawing: M.A. Fedde</p>	<p>Date: 2/25/08</p>	<p>File: SF-BGA60C-B-61 Dwg.mcd</p>	<p>Modified: 07/01/14</p>